Medium Voltage High Capacitance for General Use Specifications and Test Methods

No.	Ite	m	Specifications	Test Method
1	Operating Temperature Range		−55 to +125°C	-
2	Appearance		No defects or abnormalities	Visual inspection
3	Dimensions		Within the specified dimensions	Using calipers and micrometers
4	Dielectric Strength		No defects or abnormalities	No failure should be observed when 150% of the rated voltage (200% of the rated voltage in case of rated voltage: DC200V, DC250V, 120% of the rated voltage in case of rated voltage: DC1kV) is applied between the terminations for 1 to 5 sec., provided the charge/discharge current is less than 50mA.
5	Insulation Resistance (I.R.)		C≥0.01μF: More than 100MΩ • μF C<0.01μF: More than 10,000MΩ	The insulation resistance should be measured with rated voltage (DC500±50V in case of rated voltage: DC630V, DC1kV) and within 60±5 sec. of charging.
6	Capacitance		Within the specified tolerance	The second of th
7	Dissipation Factor (D.F.)		0.025 max.	The capacitance/D.F. should be measured at a frequency of 1±0.2kHz and a voltage of AC1±0.2V(r.m.s.).
8				The capacitance measurement should be made at each step specified in the Table.
				Step Temperature (°C)
	Capacitar	nce	Cap. Change	1 25±2 2 Min. Operating Temp.±3
	Temperat		Within ±15%	3 25±2
	Characteristics		(Temp. Range: -55 to +125°C)	4 Max. Operating Temp.±2 5 25±2
				•Pretreatment Perform a heat treatment at 150±°10°C for 60±5 min. and then let sit for 24±2 hrs. at room condition.*
9	Adhesive Strength of Termination		No removal of the terminations or other defect should occur.	Solder the capacitor to the testing jig (glass epoxy board) shown in Fig. 1. Then apply 10N force in the direction of the arrow. The soldering should be done using the reflow method and should be conducted with care so that the soldering is uniform and free of defects such as heat shock. 10N (5N: Size 1.6×0.8mm only), 10±1s Glass Epoxy Board Fig. 1
10		Appearance	No defects or abnormalities	Solder the capacitor to the test jig (glass epoxy board).
	Vibration Resistance	Capacitance	Within the specified tolerance	The capacitor should be subjected to a simple harmonic motion
		·	0.025 max.	having a total amplitude of 1.5mm, the frequency being varied uniformly between the approximate limits of 10 and 55Hz. The frequency range, from 10 to 55Hz and return to 10Hz, should be traversed in approximately 1 min. This motion should be applied for a period of 2 hrs. in each of 3 mutually perpendicular directions (total of 6 hrs.).
				Solder resist Glass Epoxy Board

^{* &}quot;Room condition" Temperature: 15 to 35°C, Relative humidity: 45 to 75%, Atmospheric pressure: 86 to 106kPa

Continued on the following page.



Medium Voltage High Capacitance for General Use Specifications and Test Methods

 $\begin{tabular}{|c|c|c|c|} \hline \end{tabular}$ Continued from the preceding page.

No. Item Specifications No marking defects Solder the capacitor to the testing jig (glass e in Fig. 2. Then apply a force in the direction shown in The soldering should be done using the refloshould be conducted with care so that the so and free of defects such as heat should be conducted with care so that the so and free of defects such as heat should be conducted with care so that the so and free of defects such as heat should be conducted with care so that the so and free of defects such as heat should be conducted with care so that the so and free of defects such as heat should be conducted with care so that the so and free of defects such as heat should be conducted with care so that the so and free of defects such as heat should be conducted with care so that the so and free of defects such as heat should be conducted with care so that the so and free of defects such as heat should be conducted with care so that the so and free of defects such as heat should be conducted with care so that the so and free of defects such as heat should be conducted with care so that the so and free of defects such as heat should be conducted with care so that the so and free of defects such as heat should be conducted with care so that the so and free of defects such as heat should be conducted with care so that the so and free of defects such as heat should be conducted with care so that the so and free of defects such as heat should be conducted with care so that the so and free of defects such as heat should be conducted with care so that the so and free of defects such as heat should be conducted with care so that the so and free of defects such as heat should be conducted with care so that the so and free of defects such as heat should be conducted with care so that the so and free of defects such as heat should be conducted with care so that the so and free of defects such as heat should be conducted with care so that the solution of the should be conducted with care so that the solution should be conducted with	n Fig. 3. flow method and soldering is uniform and soldering is uniform (in mm) nol (JIS-K-8101) and opportion).
In Fig. 2. Then apply a force in the direction shown in The soldering should be done using the reflo should be conducted with care so that the so and free of defects such as heat shock. LxW Dimension (mm)	n Fig. 3. flow method and soldering is uniform and soldering is uniform (in mm) nol (JIS-K-8101) and opportion).
rosin (JIS-K-5902) (25% rosin in weight prop	pportion).
Solderability of Termination 75% of the terminations are to be soldered evenly and continuously. Immerse in solder solution for 2±0.5 sec. Immersing speed: 25±2.5mm/s Temp. of solder: 245±5°C Lead Free Solder 235±5°C H60A or H63A Eu	
Appearance No marking defects Capacitance Change Within ±10% Preheat the capacitor at 120 to 150°C* for 1 Immerse the capacitor in solder solution at 2 sec. Let sit at room condition* for 24±2 hrs., 1 •Immersing speed: 25±2.5mm/s	260±5°C for 10±1
D.F. 0.025 max. •Pretreatment	
to Soldering Heat I.R. $C ≥ 0.01 μF$: More than $100 MΩ • μF$ $C < 0.01 μF$: More than $10,000 MΩ$ Perform a heat treatment at $150 ± 18°C$ for 60 let sit for $24 ± 2$ hrs. at room condition.*	60±5 min. and then
*Preheating for more than 3.2×2.5mm	
Dielectric Strength In accordance with item No.4 Step Temperature 1 100 to 120°C 2 170 to 200°C	Time 1 min. 1 min.
Appearance No marking defects Fix the capacitor to the supporting jig (glass e	epoxy board) shown
Capacitance Change Within ±7.5% in Fig. 4. Perform the 5 cycles according to the 4 heat the following table.	at treatments listed in
D.F. 0.025 max. Let sit for 24±2 hrs. at room condition,* then	n measure.
I.R. $C≥0.01μF$: More than $100MΩ • μF$ $C<0.01μF$: More than $10,000MΩ$ 1 Min. Operating Temp.±3	Time (min.) 30±3
2 Room Temp. 3 Max. Operating Temp.±2	2 to 3 30±3
Temperature Cycle Temperature Cycle 4 Room Temp. Pretreatment Perform a heat treatment at 150±18°C for 6 let sit for 24±2 hrs. at room condition.*	2 to 3
Dielectric Strength In accordance with item No.4 Cu Glass Epoxy Board Fig. 4	er resist
Appearance No marking defects	
Capacitance Change Within ±15% Let the capacitor sit at 40±2°C and relative hur for 500±2°d hrs.	numidity of 90 to 95%
Humidity 15 (Steady D.F. 0.05 max. Remove and let sit for 24±2 hrs. at room con measure.	ondition,* then
State) State) I.R. $C \ge 0.01 \mu F$: More than $10 M \Omega \cdot \mu F$ Pretreatment $C < 0.01 \mu F$: More than $1,000 M \Omega$ Perform a heat treatment at $150 \pm_1 \% C$ for $6 + 10 + 10 = 10$.	60±5 min. and then
Dielectric Strength In accordance with item No.4	

 $^{^{\}star}$ "Room condition" Temperature: 15 to 35°C, Relative humidity: 45 to 75%, Atmospheric pressure: 86 to 106kPa

Continued on the following page.



Medium Voltage High Capacitance for General Use Specifications and Test Methods

Continued from the preceding page.

No.	Item		Specifications	Test Method
	Life	Appearance	No marking defects	Apply 120% of the rated voltage (150% of the rated voltage in case of rated voltage: DC200V, DC250V, 110% of the rated voltage in case of rated voltage: DC1kV) for 1,000±48hrs. at maximum operating temperature ±3°C. Remove and let sit for 24±2hrs. at room condition,* then measure. The charge/discharge current is less than 50mA. •Pretreatment Apply test voltage for 60±5 min. at test temperature. Remove and let sit for 24±2 hrs. at room condition.*
		Capacitance Change	Within ±15% (rated voltage: DC200V, DC250V, DC500V, DC630V) Within ±20% (rated voltage: DC1kV)	
16		D.F.	0.05 max.	
		I.R.	C≥0.01μF: More than $10M\Omega \cdot \mu F$ C<0.01μF: More than $1,000M\Omega$	
		Dielectric Strength	In accordance with item No.4	
17	Humidity Loading (Application: DC250V, DC630V item)	Appearance	No marking defects	Apply the rated voltage at 40±2°C and relative humidity of 90 to 95% for 500±26hrs. Remove and let sit for 24±2 hrs. at room condition,* then measure. •Pretreatment Apply test voltage for 60±5 min. at test temperature. Remove and let sit for 24±2 hrs. at room condition.*
		Capacitance Change	Within ±15%	
		D.F.	0.05 max.	
		I.R.	C≧0.01μF: More than 10MΩ • μF C<0.01μF: More than 1,000MΩ	
		Dielectric Strength	In accordance with item No.4	

 $^{^{*}}$ "Room condition" Temperature: 15 to 35°C, Relative humidity: 45 to 75%, Atmospheric pressure: 86 to 106kPa